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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Obsolete
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	SCI, SPI
Peripherals	LVD, POR, PWM
Number of I/O	24
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	384 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	28-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	28-TSSOP
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc908qc8vdre

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Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



General Description



All port pins can be configured with internal pullup

PTC not available on 16-pin devices (see note in 11.1 Introduction)

PTD not available on 16-pin or 20-pin devices (see note in 11.1 Introduction)

Figure 1-1. Block Diagram



Memory







Memory

Addr.	Register Name		Bit 7	6	5	4	3	2	1	Bit 0
	LVI Status Register	Read:	LVIOUT	0	0	0	0	0	0	R
\$FE0C	(LVISR)	Write:								
	See page 95.	Reset:	0	0	0	0	0	0	0	0
\$FE0D ↓ \$FE0F	Reserved									
\$FFBE	FLASH Block Protect Register (FLBPR)	Read: Write:	BPR7	BPR6	BPR5	BPR4	BPR3	BPR2	BPR1	BPR0
	See page 41.	Reset:				Unaffecte	d by reset			
\$FFBF										
		L				I				
\$FFC0	Internal Oscillator Trim Value	Read: Write:	TRIM7	TRIM6	TRIM5	TRIM4	TRIM3	TRIM2	TRIM1	TRIM0
		Reset:			FLASH locat	ion with facto	ry programme	ed trim value.		
\$FFC1										
		L								
	COP Control Register	Read:			LO	W BYTE OF I	RESET VECT	OR		
\$FFFF	(COPCTL)	Write:			WRITING C	LEARS COP	COUNTER (A	NY VALUE)		
	See page 65.	Reset:				Unaffecte	d by reset			

Figure 2-2. Control, Status, and Data Registers (Sheet 8 of 8)

= Unimplemented

= Reserved

U = Unaffected

R

FLASH Memory (FLASH)



PGM — Program Control Bit

This read/write bit configures the memory for program operation. PGM is interlocked with the ERASE bit such that both bits cannot be equal to 1 or set to 1 at the same time.

- 1 = Program operation selected
- 0 = Program operation unselected

2.6.2 FLASH Page Erase Operation

Use the following procedure to erase a page of FLASH memory. A page consists of 64 consecutive bytes starting from addresses \$XX00, \$XX40, \$XX80, or \$XXC0. The 48-byte user interrupt vectors area also forms a page. Any FLASH memory page can be erased alone.

- 1. Set the ERASE bit and clear the MASS bit in the FLASH control register.
- 2. Read the FLASH block protect register.
- 3. Write any data to any FLASH location within the address range of the block to be erased.
- 4. Wait for a time, t_{NVS}.
- 5. Set the HVEN bit.
- 6. Wait for a time, t_{Erase}.
- 7. Clear the ERASE bit.
- 8. Wait for a time, t_{NVH}.
- 9. Clear the HVEN bit.
- 10. After time, t_{BCV}, the memory can be accessed in read mode again.

NOTE

Programming and erasing of FLASH locations cannot be performed by code being executed from the FLASH memory. While these operations must be performed in the order as shown, other unrelated operations may occur between the steps.

NOTE

A page erase of the vector page will erase the internal oscillator trim value at \$FFC0.



Memory







Chapter 4 Configuration Registers (CONFIG1 and CONFIG2)

4.1 Introduction

This section describes the configuration registers (CONFIG1 and CONFIG2). The configuration registers enable or disable the following options:

- Stop mode recovery time (32 × BUSCLKX4 cycles or 4096 × BUSCLKX4 cycles)
- STOP instruction
- Computer operating properly module (COP)
- COP reset period (COPRS): 8176 × BUSCLKX4 or 262,128 × BUSCLKX4
- Low-voltage inhibit (LVI) enable and trip voltage selection
- · Allow clock source to remain enabled in STOP
- Enable IRQ pin
- Disable IRQ pin pullup device
- Enable RST pin
- Clock source selection for the enhanced serial communication interface (ESCI) module
- Reposition TIM2 timer channels

4.2 Functional Description

The configuration registers are used in the initialization of various options. The configuration registers can be written once after each reset. Most of the configuration register bits are cleared during reset. Since the various options affect the operation of the microcontroller unit (MCU) it is recommended that this register be written immediately after reset. The configuration registers are located at \$001E and \$001F, and may be read at anytime.

NOTE

The CONFIG registers are one-time writable by the user after each reset. Upon a reset, the CONFIG registers default to predetermined settings as shown in Figure 4-1 and Figure 4-2.



Figure 4-1. Configuration Register 2 (CONFIG2)



External Interrupt (IRQ)



8.6 KBI During Break Interrupts

The system integration module (SIM) controls whether status bits in other modules can be cleared during the break state. The BCFE bit in the break flag control register (BFCR) enables software to clear status bits during the break state. See BFCR in the SIM section of this data sheet.

To allow software to clear status bits during a break interrupt, write a 1 to BCFE. If a status bit is cleared during the break state, it remains cleared when the MCU exits the break state.

To protect status bits during the break state, write a 0 to BCFE. With BCFE cleared (its default state), software can read and write registers during the break state without affecting status bits. Some status bits have a two-step read/write clearing procedure. If software does the first step on such a bit before the break, the bit cannot change during the break state as long as BCFE is cleared. After the break, doing the second step clears the status bit.

8.7 I/O Signals

The KBI module can share its pins with the general-purpose I/O pins. See Figure 8-2 for the port pins that are shared.

8.7.1 KBI Input Pins (KBI7:KBI0)

Each KBI pin is independently programmable as an external interrupt source. KBI pin polarity can be controlled independently. Each KBI pin when enabled will automatically configure the appropriate pullup/pulldown device based on polarity.

8.8 Registers

The following registers control and monitor operation of the KBI module:

- KBSCR (keyboard interrupt status and control register)
- KBIER (keyboard interrupt enable register)
- KBIPR (keyboard interrupt polarity register)

8.8.1 Keyboard Status and Control Register (KBSCR)

Features of the KBSCR:

- Flags keyboard interrupt requests
- Acknowledges keyboard interrupt requests
- Masks keyboard interrupt requests
- Controls keyboard interrupt triggering sensitivity



8.8.3 Keyboard Interrupt Polarity Register (KBIPR)

KBIPR determines the polarity of the enabled keyboard interrupt pin and enables the appropriate pullup or pulldown device.



Figure 8-5. Keyboard Interrupt Polarity Register (KBIPR)

KBIP5–KBIP0 — Keyboard Interrupt Polarity Bits

Each of these read/write bits enables the polarity of the keyboard interrupt detection.

1 = Keyboard polarity is high level and/or rising edge

0 = Keyboard polarity is low level and/or falling edge



PTD[7:0] — Port D Data Bits

These read/write bits are software programmable. Data direction of each port D pin is under the control of the corresponding bit in data direction register D. Reset has no effect on port D data.

11.6.2 Data Direction Register D

Data direction register D (DDRD) determines whether each port D pin is an input or an output. Writing a 1 to a DDRD bit enables the output buffer for the corresponding port D pin; a 0 disables the output buffer.



Figure 11-14. Data Direction Register D (DDRD)

DDRD[7:0] — Data Direction Register D Bits

These read/write bits control port D data direction. Reset clears DDRD[7:0], configuring all port D pins as inputs.

1 = Corresponding port D pin configured as output

0 = Corresponding port D pin configured as input

NOTE

Avoid glitches on port D pins by writing to the port D data register before changing data direction register D bits from 0 to 1. Figure 11-15 shows the port D I/O logic.



Figure 11-15. Port D I/O Circuit

When DDRDx is a 1, reading address \$0003 reads the PTDx data latch. When DDRDx is a 0, reading address \$0003 reads the voltage level on the pin. The data latch can always be written, regardless of the state of its data direction bit.



14.3.1 Bus Timing

In user mode, the internal bus frequency is the oscillator frequency (BUSCLKX4) divided by four.

14.3.2 Clock Start-Up from POR

When the power-on reset module generates a reset, the clocks to the CPU and peripherals are inactive and held in an inactive phase until after the 4096 BUSCLKX4 cycle POR time out has completed. The IBUS clocks start upon completion of the time out.

14.3.3 Clocks in Stop Mode and Wait Mode

Upon exit from stop mode by an interrupt or reset, the SIM allows BUSCLKX4 to clock the SIM counter. The CPU and peripheral clocks do not become active until after the stop delay time out. This time out is selectable as 4096 or 32 BUSCLKX4 cycles. See 14.7.2 Stop Mode.

In wait mode, the CPU clocks are inactive. The SIM also produces two sets of clocks for other modules. Refer to the wait mode subsection of each module to see if the module is active or inactive in wait mode. Some modules can be programmed to be active in wait mode.

14.4 Reset and System Initialization

The MCU has these reset sources:

- Power-on reset module (POR)
- External reset pin (RST)
- Computer operating properly module (COP)
- Low-voltage inhibit module (LVI)
- Illegal opcode
- Illegal address

All of these resets produce the vector \$FFFE_FFF (\$FEFE_FEFF in monitor mode) and assert the internal reset signal (IRST). IRST causes all registers to be returned to their default values and all modules to be returned to their reset states.

An internal reset clears the SIM counter (see 14.5 SIM Counter), but an external reset does not. Each of the resets sets a corresponding bit in the SIM reset status register (SRSR). See 14.8 SIM Registers.

14.4.1 External Pin Reset

The \overline{RST} pin circuits include an internal pullup device. Pulling the asynchronous \overline{RST} pin low halts all processing. The PIN bit of the SIM reset status register (SRSR) is set as long as \overline{RST} is held low for at least the minimum t_{RL} time. Figure 14-3 shows the relative timing. The \overline{RST} pin function is only available if the RSTEN bit is set in the CONFIG2 register.

RST
Figure 14-3. External Reset Timing



14.6.2.1 Interrupt Status Register 1

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	IF6	IF5	IF4	IF3	IF2	IF1	0	0
Write:	R	R	R	R	R	R	R	R
Reset:	0	0	0	0	0	0	0	0
	R	= Reserved						

Figure 14-11. Interrupt Status Register 1 (INT1)

IF1–IF6 — Interrupt Flags

These flags indicate the presence of interrupt requests from the sources shown in Table 14-3.

1 = Interrupt request present

0 = No interrupt request present

Bit 0 and 1— Always read 0

14.6.2.2 Interrupt Status Register 2

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	IF14	IF13	IF12	IF11	IF10	IF9	IF8	IF7
Write:	R	R	R	R	R	R	R	R
Reset:	0	0	0	0	0	0	0	0
	R	= Reserved						

Figure 14-12. Interrupt Status Register 2 (INT2)

IF7–IF14 — Interrupt Flags

This flag indicates the presence of interrupt requests from the sources shown in Table 14-3.

1 = Interrupt request present

0 = No interrupt request present

14.6.2.3 Interrupt Status Register 3

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	IF22	IF21	IF20	IF19	IF18	IF17	IF16	IF15
Write:	R	R	R	R	R	R	R	R
Reset:	0	0	0	0	0	0	0	0
	R	= Reserved						

Figure 14-13. Interrupt Status Register 3 (INT3)

IF22–IF15 — Interrupt Flags

These flags indicate the presence of interrupt requests from the sources shown in Table 14-3.

1 = Interrupt request present

0 = No interrupt request present

14.6.3 Reset

All reset sources always have equal and highest priority and cannot be arbitrated.



System Integration Module (SIM)

14.8.2 Break Flag Control Register

The break control register (BFCR) contains a bit that enables software to clear status bits while the MCU is in a break state.



Figure 14-20. Break Flag Control Register (BFCR)

BCFE — Break Clear Flag Enable Bit

This read/write bit enables software to clear status bits by accessing status registers while the MCU is in a break state. To clear status bits during the break state, the BCFE bit must be set.

- 1 = Status bits clearable during break
- 0 = Status bits not clearable during break



16.6 TIM1 During Break Interrupts

A break interrupt stops the counter and inhibits input captures.

The system integration module (SIM) controls whether status bits in other modules can be cleared during the break state. The BCFE bit in the break flag control register (BFCR) enables software to clear status bits during the break state. See BFCR in the SIM section of this data sheet.

To allow software to clear status bits during a break interrupt, write a 1 to BCFE. If a status bit is cleared during the break state, it remains cleared when the MCU exits the break state.

To protect status bits during the break state, write a 0 to BCFE. With BCFE cleared (its default state), software can read and write registers during the break state without affecting status bits. Some status bits have a two-step read/write clearing procedure. If software does the first step on such a bit before the break, the bit cannot change during the break state as long as BCFE is cleared. After the break, doing the second step clears the status bit.

16.7 I/O Signals

The TIM1 module can share its pins with the general-purpose I/O pins. See Figure 16-1 for the port pins that are shared.

16.7.1 TIM1 Channel I/O Pins (T1CH3:T1CH0)

Each channel I/O pin is programmable independently as an input capture pin or an output compare pin. T1CH0 and T1CH2 can be configured as buffered output compare or buffered PWM pins.

16.7.2 TIM1 Clock Pin (T1CLK)

T1CLK is an external clock input that can be the clock source for the counter instead of the prescaled internal bus clock. Select the T1CLK input by writing 1s to the three prescaler select bits, PS[2:0]. The Timer Interface Module Characteristics table in the Electricals section. The maximum T1CLK frequency is the least of 4 MHz or bus frequency ÷ 2.

16.8 Registers

The following registers control and monitor operation of the TIM1:

- TIM1 status and control register (T1SC)
- TIM1 control registers (T1CNTH:T1CNTL)
- TIM1 counter modulo registers (T1MODH:T1MODL)
- TIM1 channel status and control registers (T1SC0 through T1SC3)
- TIM1 channel registers (T1CH0H:T1CH0L through T1CH3H:T1CH3L)

16.8.1 TIM1 Status and Control Register

The TIM1 status and control register (T1SC) does the following:

- Enables TIM1 overflow interrupts
- Flags TIM1 overflows
- Stops the counter
- Resets the counter
- Prescales the counter clock



Development Support

Mode	Mode (RTAD) (RTAD) Veste		Reset	Serial Communi- cation	Mc Sele	ode ction	СОР	Communication Speed		ו	Comments	
	(FTA2)	(FTA3)	vector	PTA0	PTA1	PTA4		External Clock	Bus Frequency	Baud Rate		
Normal Monitor	V _{TST}	V _{DD}	х	1	1	0	Disabled	9.8304 MHz	2.4576 MHz	9600	Provide external clock at OSC1.	
Forced	V _{DD}	Х	\$FFFF (blank)	1	х	x	Disabled	9.8304 MHz	2.4576 MHz	9600	Provide external clock at OSC1.	
Monitor	V _{SS}	х	\$FFFF (blank)	1	x	x	Disabled	х	3.2 MHz (Trimmed)	9600	Internal clock is active.	
User	х	х	Not \$FFFF	x	x	x	Enabled	х	х	х		
MON08 Function [Pin No.]	V _{TST} [6]	RST [4]		COM [8]	MOD 0 [12]	MOD 1 [10]		OSC1 [13]				

 Table 18-1. Monitor Mode Signal Requirements and Options

1. PTA0 must have a pullup resistor to V_{DD} in monitor mode.

2. Communication speed in the table is an example to obtain a baud rate of 9600. Baud rate using external oscillator is bus frequency / 256 and baud rate using internal oscillator is bus frequency / 335.

3. External clock is a 9.8304 MHz oscillator on OSC1.

4. X = don't care

5. MON08 pin refers to P&E Microcomputer Systems' MON08-Cyclone 2 by 8-pin connector.

NC	1	2	GND
NC	3	4	RST
NC	5	6	IRQ
NC	7	8	PTA0
NC	9	10	PTA4
NC	11	12	PTA1
OSC1	13	14	NC
V_{DD}	15	16	NC

The rising edge of the internal RST signal latches the monitor mode. Once monitor mode is latched, the values on PTA1 and PTA4 pins can be changed.

Once out of reset, the MCU waits for the host to send eight security bytes (see 18.3.2 Security). After the security bytes, the MCU sends a break signal (10 consecutive 0s) to the host, indicating that it is ready to receive a command.

18.3.1.1 Normal Monitor Mode

RST and OSC1 functions will be active on the PTA3 and PTA5 pins respectively as long as V_{TST} is applied to the IRQ pin. If the IRQ pin is lowered (no longer V_{TST}) then the chip will still be operating in monitor mode, but the pin functions will be determined by the settings in the configuration registers (see Chapter 4 Configuration Registers (CONFIG1 and CONFIG2)) when V_{TST} was lowered. With V_{TST} lowered, the BIH and BIL instructions will read the IRQ pin state only if IRQEN is set in the CONFIG2 register.



Electrical Specifications

Characteristic ⁽¹⁾	Symbol	Min	Typ ⁽²⁾	Мах	Unit
DC injection current ⁽³⁾ (4) (5) (6) Single pin limit $V_{in} > V_{DD}$ $V_{in} < V_{SS}$	l _{ic}	0 0		2 -0.2	mA
V _{in} > V _{DD} V _{in} < V _{SS}		0 0		25 5	
Ports Hi-Z leakage current	IIL	0		±1	μA
Capacitance Ports (as input) ⁽³⁾	C _{IN}	_	_	8	pF
POR rearm voltage	V _{POR}	750		_	mV
POR rise time ramp rate ⁽³⁾⁽⁷⁾	R _{POR}	0.035			V/ms
Monitor mode entry voltage ⁽³⁾	V _{TST}	V _{DD} + 2.5	—	9.1	V
Pullup resistors ⁽⁸⁾ PTA0–PTA5, PTB0–PTB7, PTC3–PTC0, PTD7–PTD0	R _{PU}	16	26	36	kΩ
Pulldown resistors ⁽⁶⁾ PTA0–PTA5	R _{PD}	16	26	36	kΩ
Low-voltage inhibit reset, trip falling voltage ⁽⁹⁾	V _{TRIPF}	3.90	4.20	4.50	V
Low-voltage inhibit reset, trip rising voltage	V _{TRIPR}	4.00	4.30	4.60	V
Low-voltage inhibit reset/recover hysteresis	V _{HYS}	_	100		mV

1. V_{DD} = 4.5 to 5.5 Vdc, V_{SS} = 0 Vdc, T_A = T_L to T_H , unless otherwise noted.

- 2. Typical values reflect average measurements at midpoint of voltage range, 25 Conly. Typical values are for reference only and are not tested in production.
- 3. Values are based on characterization results, not tested in production.
- 4. All functional non-supply pins are internally clamped to V_{SS} and V_{DD} .
- 5. Input must be current limited to the value specified. To determine the value of the required current-limiting resistor, calculate resistance values for positive and negative clamp voltages, then use the larger of the two values.
- 6. Power supply must maintain regulation within operating V_{DD} range during instantaneous and operating maximum current conditions. If positive injection current (V_{in} > V_{DD}) is greater than I_{DD}, the injection current may flow out of V_{DD} and could result in external power supply going out of regulation. Ensure external V_{DD} load will shunt current greater than maximum injection current. This will be the greatest risk when the MCU is not consuming power. Examples are: if no system clock is present, or if clock rate is very low (which would reduce overall power consumption).
- 7. If minimum V_{DD} is not reached before the internal POR reset is released, the LVI will hold the part in reset until minimum V_{DD} is reached.
- 8. R_{PU} and R_{PD} is measured at V_{DD} = 5.0 V. Pulldown resistors only available when KBIx is enabled with KBIxPOL =1.
- 9. Functionality of MCU guaranteed by production test down to minimum LVI trip point. The electrical parameters are only guaranteed within the specified operating voltage range.





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NOTES:

- 1. DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- A. THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
- 4. 751F-01 THRU -04 OBSOLETE. NEW STANDARD: 751F-05
- A. THIS DIMENSION DOES NOT INCLUDE DAM BAR PROTRUSION ALLOWABLE DAM BAR PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF THIS DIMENSION AT MAXIMUM MATERIAL CONDITION.

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CASEOUTLINE	S	STANDARD: MS-013AE				



NOTES:

1. CONTROLLING DIMENSION: MILLIMETER

2. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M-1982.

3 DIMENSION DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.

 $\frac{4}{4}$ dimension does not include interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.25 per side.

5 DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF THE DIMENSION AT MAXIMUM MATERIAL CONDITION.

6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY

7 \setminus dimensions are to be determined at datum plane [-w-

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